

# 6-Channel White LED Driver for up to 72 LEDs





## BD6583MUV-A

#### General Description

BD6583MUV-A is white LED driver IC with PWM step-up DC/DC converter that can boost max 42.5V and current driver that can drive max 25mA. The wide and precision brightness can be controlled by external PWM pulse. BD6583MUV-A has very accurate current drivers, and it has few current errors between each strings. So, it will be helpful to reduce brightness spots on the LCD. Small package type is suited for saving space.

#### Features

- High efficiency PWM step-up DC/DC converter (fsw=1MHz), max efficiency 93%
- High accuracy & good matching (±3%) current drivers 6ch
- Drive up to 12 in series, 6 strings in parallel =72 white LEDs (white LED Vf=3.5Vmax)
- Rich safety functions
  - Over-voltage protection (OVP)
  - Over current limit
  - External SBD open detect
  - Thermal shutdown

#### Key Specifications

■ Operating power supply voltage range: 2.7V to 22.0V
 ■ LED Maximum Current: 25mA (Max.)
 ■ Quiescent Current 1: 0.6µA (Typ.)
 Quiescent Current 2: 4.6µA (Typ.)
 ■ Operating temperature range: -30°C to +85°C

● Package W(Typ.) x T(Typ.) x H(Max.)



#### VQFN024V4040

4.00mm x 4.00mm x 1.00mm

Figure 1. Package

#### Applications

All middle size LCD equipments backlight of Notebook PC, portable DVD player, car navigation systems, etc.

#### Typical Application Circuit

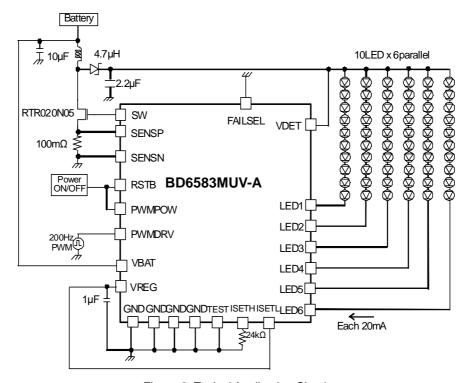


Figure 2. Typical Application Circuit

OProduct structure : Silicon monolithic integrated circuit OThis product is not designed protection against radioactive rays

● Absolute Maximum Ratings (Ta=25 °C)

Parameter	Symbol	Ratings	Unit	Condition
Terminal voltage 1	VMAX1	7	V	TEST,VREG,SENSP,SENSN,SW,RSTB, PWMPOW,PWMDRV,FAILSEL,ISETH,ISETL
Terminal voltage 2	VMAX2	25	V	LED1, LED2, LED3, LED4, LED5, LED6, VBAT
Terminal voltage 3	VMAX3	50.5	V	VDET
Power dissipation 1	Pd1	500	mW	*1
Power dissipation 2	Pd2	780	mW	*2
Power dissipation 3	Pd3	1510	mW	*3
Operating temperature range	Topr	-30 to +85	°C	
Storage temperature range	Tstg	-55 to +150	°C	·

<sup>(\*1)</sup> Reduced 4.0mW/ °C With Ta>25 °C when not mounted on a heat radiation Board.

#### ■Recommended Operating Rating (Ta=-30 °C to +85 °C)

	<u> </u>					
Doromotor	Cumbal	Ratings			Lloit	Condition
Parameter	Symbol	Min.	Тур.	Max.	Unit	Condition
Power supply voltage	VBAT	2.7	12.0	22.0	٧	

●Electrical Characteristics (Unless otherwise specified, VBAT=12V, RSTB=2.5V, Ta = +25 °C)

Parameter	Symbol		Limits	Lloi	Unit	Condition
Farameter	Symbol	Min.	Тур.	Max.	Offic	Condition
[FAILSEL,PWMDRV Terminal]						
Threshold voltage (Low)	VthL	0	-	0.2	V	
Threshold voltage (High) 1	VthH1	1.4	-	5.0	V	VBAT>5.0V
Threshold voltage (High) 2	VthH2	1.4	-	VBAT	V	VBAT<5.0V
Terminal input current	lin	-	8.3	14.0	μΑ	Input=2.5V
[PWMPOW Terminal]						
Low input voltage range	PWML	0	-	0.2	V	
High input voltage range1	PWMH1	1.4	-	5.0	V	VBAT>5.0V
High input voltage range2	PWMH2	1.4	-	VBAT	V	VBAT<5.0V
PWM pull down resistor	PWMR	300	500	700	kΩ	
[RSTB Terminal]						
Low input voltage range	RSTBL	0	-	0.2	V	
High input voltage range1	RSTBH1	2.25	2.5	5.0	V	VBAT>5.0V
High input voltage range2	RSTBH2	2.25	2.5	VBAT	V	VBAT<5.0V
Current consumption	IRSTB	-	89	134	μΑ	RSTB=2.5V, LED1-6=3V
[Regulator]	•					
VREG voltage	VREG	4.0	5.0	6.0	V	No load
Under voltage lock out	UVLO	2.05	2.25	2.65	V	

<sup>(\*2) 1</sup> layer (ROHM Standard board) has been mounted. Copper foil area 0mm², When it's used by more than Ta=25 °C, it's reduced by 6.2mW/ °C.

<sup>(\*3) 4</sup> layer (JEDEC Compliant board) has been mounted.

Copper foil area 1 layer 6.28mm², Copper foil area 2 to 4 layers 5655.04mm², When it's used by more than Ta=25 °C, it's reduced by 12.1mW/ °C.

## ● Electrical Characteristics - continued

(Unless otherwise specified, VBAT=12V, RSTB=2.5V, Ta = +25  $^{\circ}$ C)

Parameter	Cumbal	Limits			Unit	Condition	
Parameter	Symbol	Min.	Тур.	Max.	Unit	Condition	
[Switching Regulator]							
Quiescent current 1	lq1	-	0.6	3.4	μΑ	RSTB=0V, VBAT=12V	
Quiescent current 2	lq2	-	4.6	10	μΑ	RSTB=0V, VBAT=22V	
Current consumption	ldd	-	3.4	5.1	mA	VDET=0V,ISETH=24kΩ	
LED control voltage	VLED	0.4	0.5	0.6	V		
Over current limit voltage	Оср	70	100	130	mV	*1	
SBD open protect	Sop	-	-	0.1	V	Detect voltage of VDET pin	
Switching frequency	fSW	8.0	1.0	1.2	MHz		
Duty cycle limit	Duty	92.5	95.0	99.0	%	LED1-6=0.3V	
Over voltage limit	Ovl	43.0	44.7	46.4	V	LED1-6=0.3V	
[Current driver]							
LED maximum current	ILMAX	-	-	25	mA		
LED current accuracy	ILACCU	-	-	±5	%	ILED=16mA	
LED current matching	ILMAT	-	-	±3	%	<ul><li>Each LED current/Average (LED1- 6)</li><li>ILED=16mA</li></ul>	
ISET voltage	Iset	0.5	0.6	0.7	V		
LED current limiter	ILOCP	35	60	90	mA	Current limit value at ISET resistor $4.7k\Omega$ setting LED1, 2, 3, 4, 5, 6=0.5V	
LED terminal Over voltage protect	LEDOVP	10.0	11.5	13.0	V	RSTB=PWMDRV=2.5V	

<sup>\*1</sup> This parameter is tested with dc measurement.

#### Pin Descriptions

PIN Name	In/Out	PIN number	Function	Terminal equivalent circuit diagram
1	VDET	In	Detect input for SBD open and OVP	С
2	N.C.	-	No connect pin	F
3	GND	-	GND	В
4	SW	Out	Switching Tr drive terminal	G
5	SENSP	In	+ Side Current sense terminal	G
6	TEST	In	TEST input (Pull down 100kΩ to GND)	G
7	SENSN	In	- Side Current sense terminal	A
8	GND	-	GND	В
9	ISETH	In	Resistor connection for LED current setting at PWMDRV=H	А
10	ISETL	In	Resistor connection for LED current setting at PWMDRV=L	А
11	PWMDRV	In	PWM input pin for power ON/OFF only driver	Е
12	LED1	In	Current sink for LED1	С
13	LED2	In	Current sink for LED2	С
14	LED3	In	Current sink for LED3	С
15	GND	-	GND	В
16	LED4	In	Current sink for LED4	С
17	LED5	In	Current sink for LED5	С
18	LED6	In	Current sink for LED6	С
19	FAILSEL	In	Latch selectable pin of protect function	Е
20	GND	-	GND	В
21	RSTB	In	Reset pin L:Reset H:Reset cancel	Е
22	VREG	Out	Regulator output / Internal power-supply	D
23	PWMPOW	In	PWM input pin for power ON/OFF	Е
24	VBAT	In	Battery input	С
-	Thermal PAD	-	Heat radiation PAD of back side Connect to GND	-

## ●Pin ESD Type

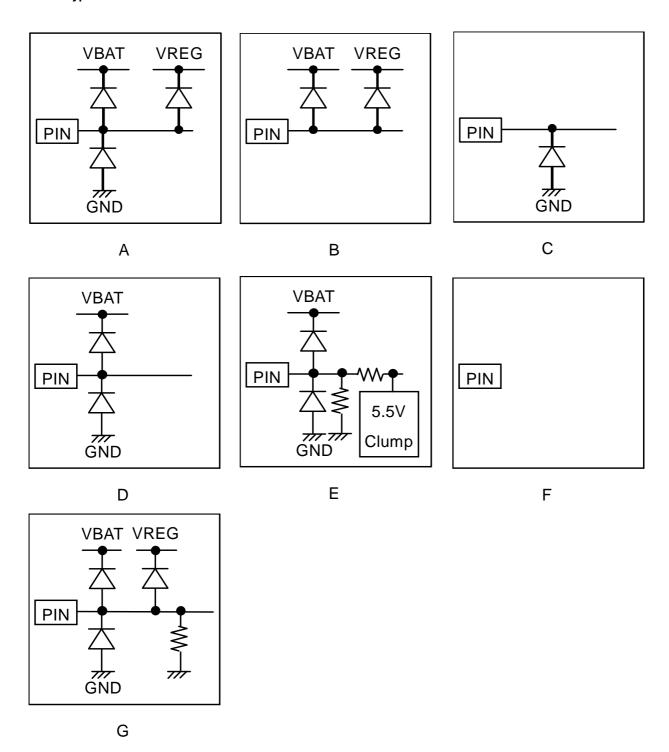
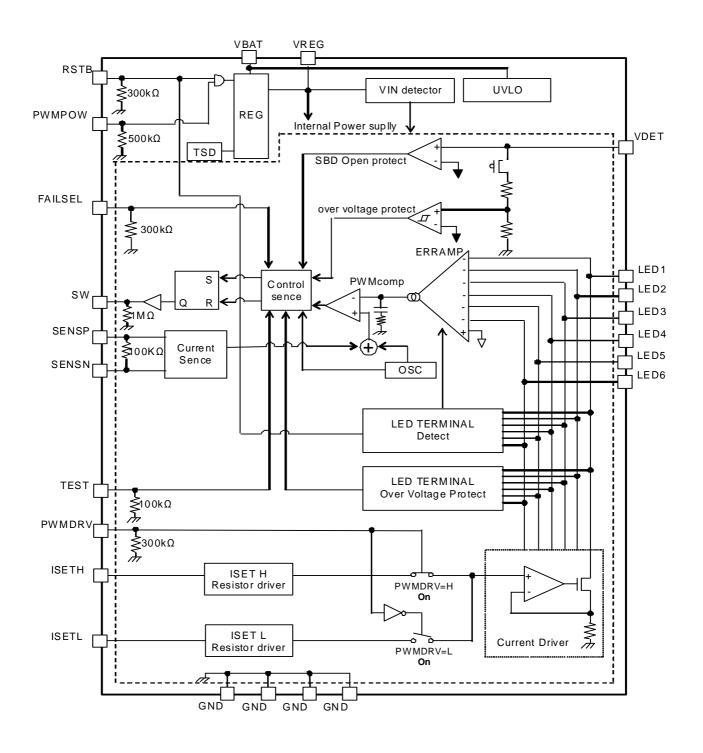


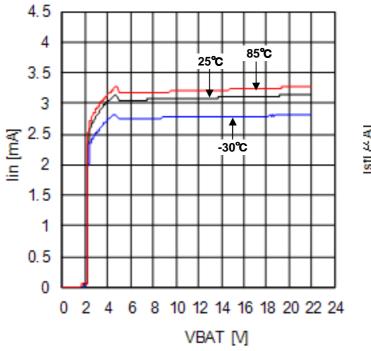
Figure 3. I/O equivalent circuit diagram

## Block Diagram



Pin number 23pin Figure 4. Block diagram

## **●**Typical Performance Curves

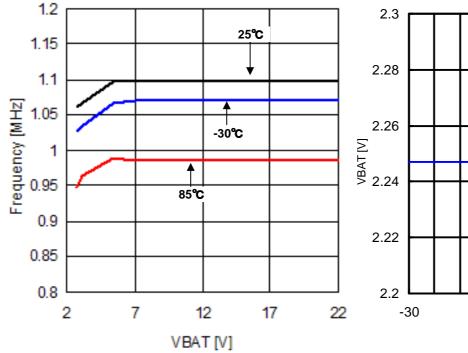


7 6 85℃ 5 25℃ IST A.A. .30°Ċ 4 3 2 1 0 2 4 6 8 10 12 14 16 18 20 22 VBAT[V]

8

Figure 5. Current Consumption vs VBAT

Figure 6. Quiescent current vs VBAT



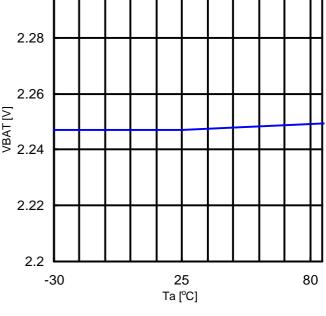
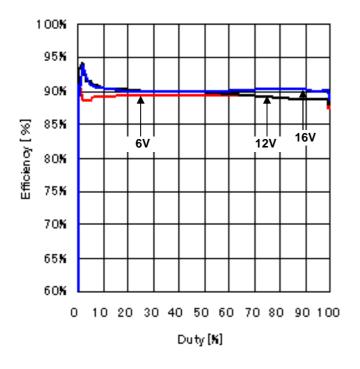


Figure 7. Oscillation frequency vs VBAT

Figure 8. UVLO vs Temperature

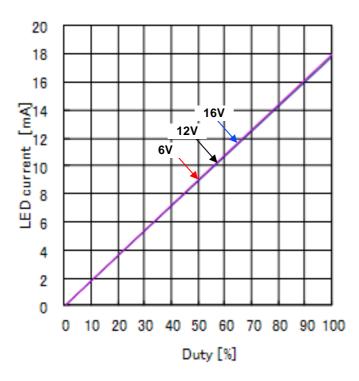
## **●**Typical Performance Curves - Continued

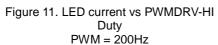


100% 95% 90% Efficiency [%] 85% 16V 12V **6V** 80% 75% 70% 65% 60% 20 40 50 60 70 80 90 100 0 10 30 Duty [%]

Figure 9. Efficiency vs PWMPOW-HI Duty ISETH=24kΩ, PWM=200Hz

Figure 10. Efficiency vs PWMDRV-HI Dutv





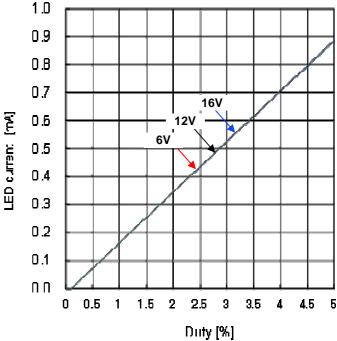


Figure 12. LED current vs PWMDRV-HI Duty (Expansion) PWM = 200Hz

## **●**Typical Performance Curves - Continued

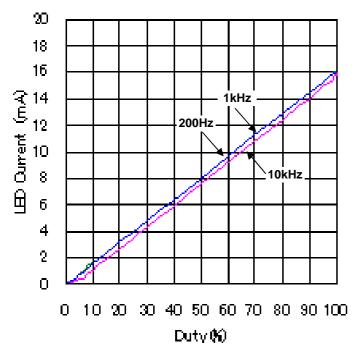


Figure 13. LED current vs PWMDRV-HI Duty PWM = 200Hz, 1kHz,10kHz

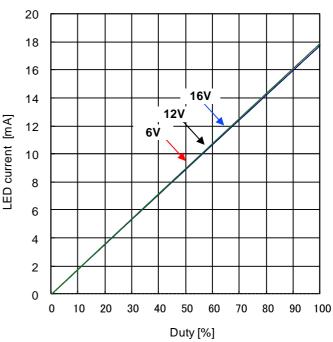


Figure 15. LED current vs PWMPOW-HI Duty TPWM = 200Hz

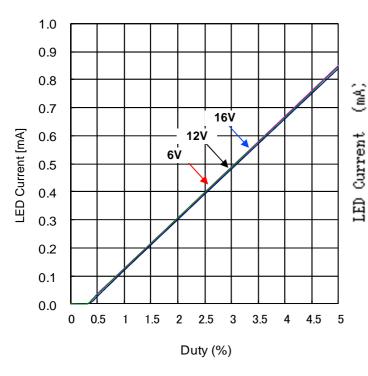


Figure 15. LED current vs PWMPOW-HI Duty (Expansion) PWM = 200Hz

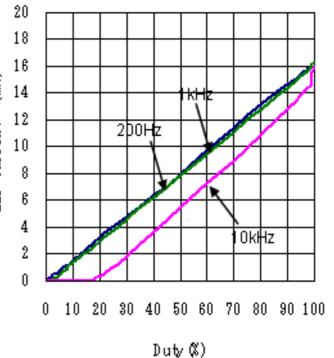


Figure 16. LED current vs PWMPOW-HI Duty PWM = 200Hz, 1kHz,10kHz

#### ● Typical Performance Curves - Continued

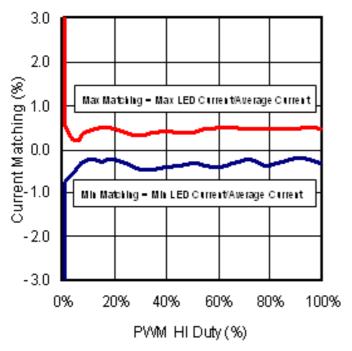


Figure 17. LED current matching vs PWMDRV-HI Duty PWM = 200Hz

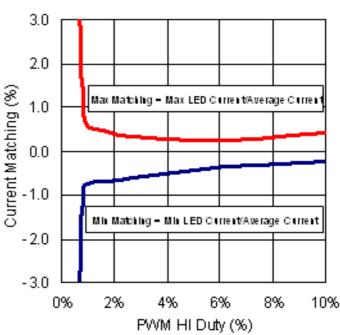


Figure 18. LED current matching vs PWMDRV-HI Duty (Expansion) PWM = 200Hz

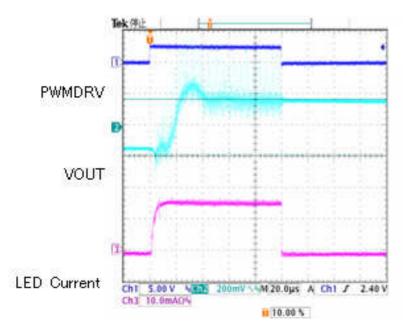


Figure 19. VOUT response
Driver Control PWM (PWMDRV)

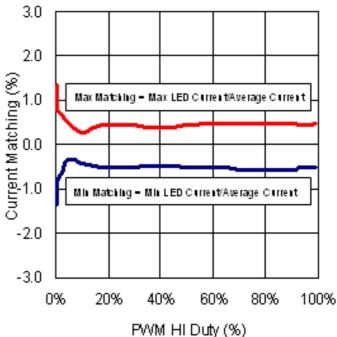


Figure 20. LED current matching vs PWMPOW-HI Duty PWM = 200Hz

## **●**Typical Performance Curves - Continued

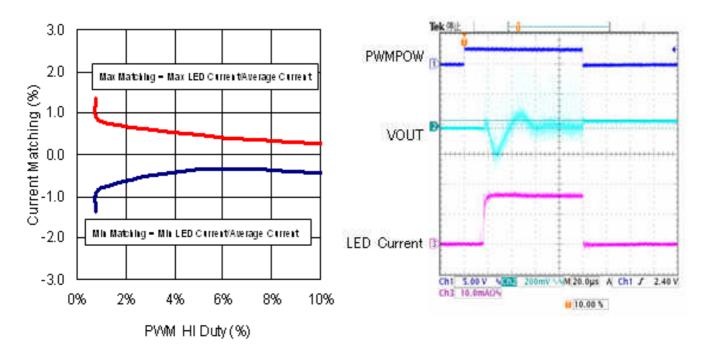


Figure 21. LED current matching vs PWMPOW-HI Duty (Expansion) PWM = 200Hz

Figure 22. VOUT response Power Control PWM (PWMPOW)

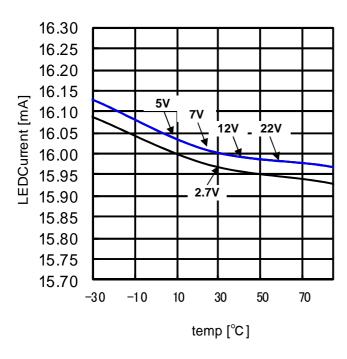


Figure 23. LED current vs Temperature PWMDRV=H, ISETH= $30k\Omega$  (16mA setting)

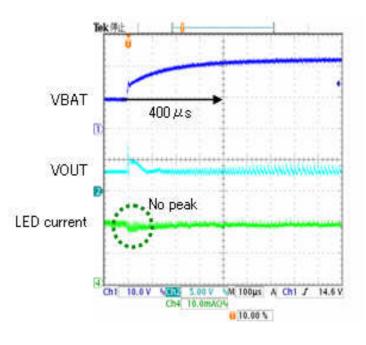


Figure 24. Line Transient (10V to 22V)

## **●**Typical Performance Curves - Continued

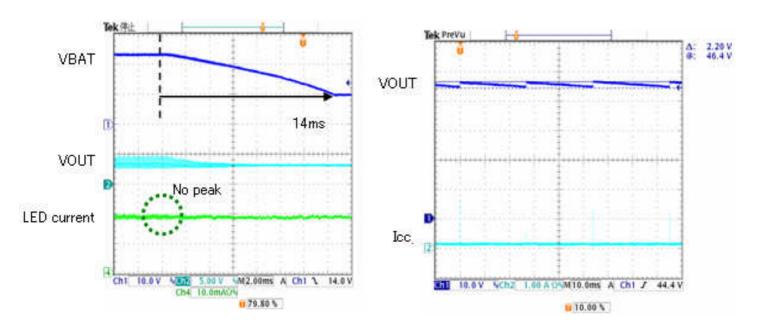


Figure 25. Line Transient (22V to 10V)

Figure 26. VOUT@OVP(LED OPEN)

#### Application example

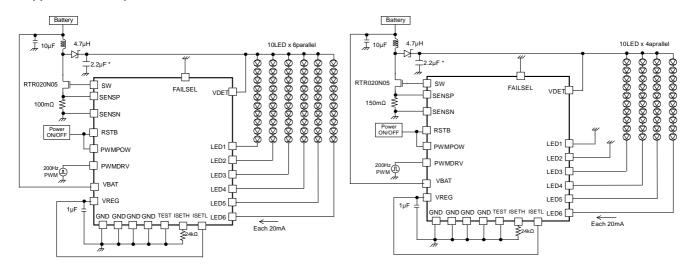


Figure 27. 10 series × 6parallel H current 20mA setting Current driver PWM application

Figure 28. 10 series × 4parallel H current 20mA setting Current driver PWM application

\* Please select the capacitor which the little bias fluctuation.

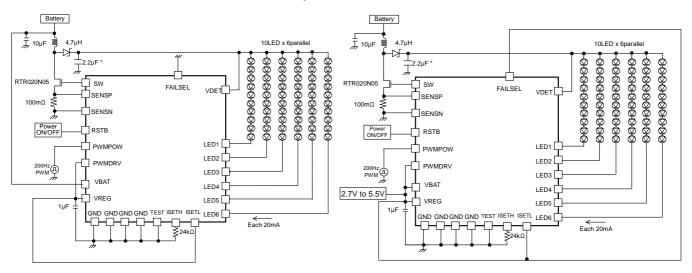


Figure 29. 10 series × 6parallel LED current 20mA setting Power control PWM application

Figure 30. Non-used Inside REG or operating under 5V application

\* Please select the capacitor which the little bias fluctuation.

## Terminal processing

TEST pin= Connect to GND

N.C. = Nothing specified in particular. Open is recommended.

VREG= When IC is driving from the outside of 2.7 to 5.5V, short VBAT and VREG, and put the voltage to VREG FAILSEL, PWMDRV= Connect to GND in case of fixing at L level. Connect to VREG of IC or the power supply of more than 1.4V in case of fixing at H level.

LED1-6= When each LED driver are not used, connect to GND of IC

GND = Each GND is connecting inside IC, but, connect to GND of all board

RSTB= RSTB is used as a power supply of internal circuit.

So, you mustn't input RSTB voltage with pull up resistor of several  $k\Omega$ .

And, please care about the relation between VBAT and RSTB enough. (ref. P16)

#### Description of Functions

#### 1) PWM current mode DC/DC converter

While BD6583MUV-A is power ON, the lowest voltage of LED1, 2, 3, 4, 5, 6 is detected, PWM duty is decided to be 0.5Vand output voltage is kept invariably. As for the inputs of the PWM comparator as the feature of the PWM current mode, one is overlapped with error components from the error amplifier, and the other is overlapped with a current sense signal that controls the inductor current into Slope waveform to prevent sub harmonic oscillation. This output controls external Nch Tr via the RS latch. In the period where external Nch Tr gate is ON, energy is accumulated in the external inductor, and in the period where external Nch Tr gate is OFF, energy is transferred to the output capacitor via external SBD.BD6583MUV-A has many safety functions, and their detection signals stop switching operation at once.

#### 2) Soft start

BD6583MUV-A has soft start function.

The soft start function prevents large coil current.

Rush current at turning on is prevented by the soft start function.

After RSTB is changed  $L \rightarrow H$ , when PWMPOW is changed  $L \rightarrow H$ , soft start becomes effective for within 1ms and soft start doesn't become effective even if PWMPOW is changed  $L \rightarrow H$  after that.

And, when the H section of PWMPOW is within 1ms, soft start becomes invalid when PWMPOW is input to H more than three times. The invalid of the soft start can be canceled by making RSTB  $\rightarrow$  L.

#### 3) FAILSEL pin

When the error condition occurs, boost operating is stopped by the protection function, and the error condition is avoided. On that occasion, the way to stop of boost operating by the protection function can be selected with FAILSEL pin. Details are as shown in Figure 31, 32.

After power ON, when the protection function is operating under about 1ms have passed, the stop state of the boost operating can be held through FAILSEL is H, the stop state can reset through RSTB is L.

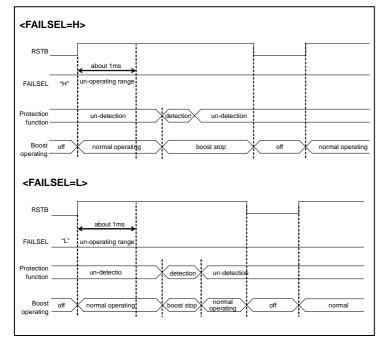
And, boost operating is stopped when the protection function is operating through FAILSEL is L, but when the protection function becomes un-detect, boost operating is started again. It never keeps holding the stop state of boost operating.

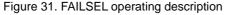
#### In PWM control by PWMDRV can't use this function.

When it is off over 10ms on PWM control by PWMPOW using this function, it may be stopped the boost operating as over current protection work at off on PWMPOW=L.

Object of protect function is as shown below.

- Over-voltage protection
- · External SBD open detect
- Thermal shutdown
- LED terminal over-voltage protection
- Over current limit





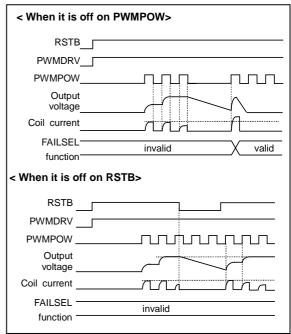


Figure 32. FAILSEL=H light off control

4) External SBD open detect and over voltage protection

BD6583MUV-A has over boost protection by external SBD open and over voltage protection. It detects VDET voltage and is stopped output Tr in abnormal condition. Details are as shown below.

External SBD open detect

In the case of external SBD is not connected to IC, the coil or external Tr may be destructed. Therefore, at such an error as VOUT becoming 0.1V or below, the Under Detector shown in the figure works, and turns off the output Tr, and prevents the coil and the IC from being destructed.

And the IC changes from activation into non-activation, and current does not flow to the coil (0mA).

Over voltage protection

At such an error of output open as the output DC/DC and the LED is not connected to IC, the DC/DC will boost too much and the VDET terminal exceed the absolute maximum ratings, and may destruct the IC. Therefore, when VDET becomes sensing voltage or higher, the over voltage limit works, and turns off the output Tr, and the pressure up made stop.

At this moment, the IC changes from activation into non-activation, and the output voltage goes down slowly. And, when the output voltage becomes the hysteresis of the over voltage limit or below, the output voltage pressure up to sensing voltage once again and unless the application error is recovered, this operation is repeated.

#### 5) Thermal shut down

BD6583MUV-A has thermal shut down function.

The thermal shut down works at 175°C or higher, and the IC changes from activation into non-activation. Because non-activation is different from RSTB=L, it doesn't' be reset inside IC. Moreover, even if thermal shut down function works, soft start, FAILSEL, selection the number of LED lines of the current driver and starting current setting at PWMDRV=L related RSTB are hold.

#### 6) Over Current Limit

Over current flows the current detection resistor that is connected to switching transistor source and between GND, SENSP pin voltage turns more than detection voltage, over current protection is operating and it is prevented from flowing more than detection current by reducing ON duty of switching Tr without stopping boost.

As over current detector of BD6583MUV-A is detected peak current, current more than over current setting value does not flow. And, over current value can decide freely by changing over current detection voltage.

<Derivation sequence of detection resistor>

Detection resistor =Over current detection voltage / Over current setting value

TYP value of over current detection voltage is 100mV, MIN = 70mV and MAX = 130mV and after the current value which was necessary for the normal operation was decided, detection resistor is derived by using MIN value of over current detection value.

For example, detection resistor when necessary current value was set at 1A is given as shown below.

Detection resistor =  $70 \text{mV} / 1 \text{A} = 70 \text{m}\Omega$ 

MAX current dispersion of this detection resistor value is

MAX current =  $\dot{130}$ mV / 70m $\Omega$  = 1.86A

<The estimate of the current value which need for the normal operation>

As over current detector of BD6583MUV-A is detected the peak current, it have to estimate peak current to flow to the coil by operating condition.

```
In case of, O Supply voltage of coil = VIN
           O Inductance value of coil = L
           O Switching frequency = fsw MIN=0.8MHz, Typ=1MHz, MAX=1.2MHz
           O Output voltage = VOUT
           O Total LED current = IOUT
           O Average current of coil = lave
           O Peak current of coil = Ipeak
           O Efficiency = eff
                                 (Please set up having margin, it refers to data on P.7)
           O ON time of switching transistor = Ton
lpeak = (VIN / L) \times (1 / fsw) \times (1-(VIN / VOUT))
lave=(VOUT x IOUT / VIN) / eff
Ton=(lave \times (1-VIN/VOUT) \times (1/fsw) \times (L/VIN) \times 2)<sup>1/2</sup>
Each current is calculated.
As peak current varies according to whether there is the direct current superposed, the next is decided.
(1-VIN/VOUT) x (1/fsw) < Ton → peak current = Ipeak /2 + lave
(1-VIN/VOUT) x (1/fsw) > Ton → peak current = Ipeak
```

In case of, VIN=6.5V, L=4.7µH, fsw=1MHz, VOUT=39V, IOUT=80mA, Efficiency=85%

lpeak =  $(6.0 \text{V} / 4.7 \mu\text{H}) \times (1 / 1 \text{MHz}) \times (1 - (6.0 \text{V} / 39 \text{V})) = 1.08 \text{A}$ 

lave =  $(39V \times 80mA / 6.0V) / 85\% = 0.61A$ 

Ton =  $(0.61A \times (1-6.0V / 39V) \times (1 / 1MHz) \times (4.7\mu H / 6.0V) \times 2)^{1/2} = 0.90\mu s$ 

 $(1-VIN/VOUT) \times (1/fsw)=0.85\mu s < Ton$ 

Peak current = 1.08A/2+0.61A = 1.15A

(Example 2)

In case of, VIN=12.0V, L=4.7µH, fsw=1MHz, VOUT=39V, IOUT=80mA, Efficiency=85%

Ipeak =  $(12.0V / 4.7\mu H) \times (1 / 1MHz) \times (1-(12V / 39V)) = 1.77A$ 

lave =  $(39V \times 80mA / 12.0V) / 85\% = 0.31A$ 

Ton =  $(0.31 \text{A} \times (1-12 \text{ V} / 39 \text{V}) \times (1 / 1 \text{MHz}) \times (4.7 \mu\text{H} / 12 \text{ V}) \times 2)^{1/2} = 0.41 \mu\text{s}$ 

 $(1-VIN/VOUT) \times (1/fsw)=0.69\mu s > Ton$ 

Peak current =  $12V/4.7\mu H \times 0.41\mu s = 1.05A$ 

\*When too large current is set, output overshoot is caused, be careful enough because it is led to break down of the IC in case of the worst.

#### Operating of the application deficiency

1) When 1 LED or 1parallel OPEN during the operating

In case of FAILSEL=L, the LED parallel which became OPEN isn't lighting, but other LED parallel is lighting. At that time, output boosts up to the over voltage protection voltage 44.7V so that LED terminal may be 0V or it boost to the output voltage that LED terminal voltage becomes LED terminal over voltage protection 11.5V or it becomes the output voltage restricted by the over current limit.

In case of FAILSEL=H, boost stops when LED becomes OPEN and all LED turns off the lights.

2) When LED short-circuited in the plural

In case of FAILSEL=L, all LED is turned on unless LED terminal voltage is LED terminal over voltage protection of more than 11.5V.

When it was more than 11.5V only the line which short-circuited is turned on normally and LED current of other lines fall or turn off the lights. In case of FAILSEL=H, boost stops at more than 11.5V and all LED turns off the lights.

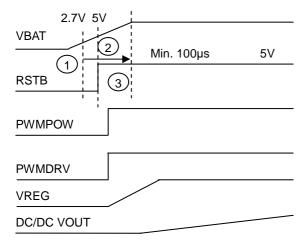
3) When Schottky diode came off

Regardless of FAILSEL, all LED isn't turned on. Also, IC and a switching transistor aren't destroyed because boost operating stops by the Schottky diode coming off protected function.

4) When over current detection resistor came off

Regardless of FAILSEL, all LED isn't turned on. Because the resistance of  $100k\Omega$  is between SENSP and SENSN terminal, over current protection works instantly and LED current can't be flow.

#### Control signal input timing



220Ω VBAT Rin GND

Figure 33. Control signal timing

Figure 34. Voltage with a control sign higher than VBAT Example corresponding to application of conditions

In case you input control signs, such as RSTB, PWMPOW, and PWMDRV, in the condition that the standup of supply voltage (VBAT) is not completed, be careful of the following point.

①Input each control signal after VBAT exceeds 2.7V.

②Please do not input each control sign until VBAT exceeds H voltage of RSTB, PWMPOW, and PWMDRV.

③When you input RSTB during the standup of VBAT and H voltage is inputted into PWMPOW, please give the standup time to stable voltage as Min.100µs 2.7V of VBAT.

There is no timing limitation at each input signal of RSTB, PWMPOW and PWMDRV.

If each control sign changes into a condition lower than VBAT in (1) and (2), it goes via the ESD custody diode by the side of VBAT of each terminal. A power supply is supplied to VBAT and there is a possibility of malfunctioning. Moreover, when the entrance current to the terminal exceeds 50mA, it has possibility to damage the LSI. In order to avoid this condition, as shown in the above figure, please insert about  $220\Omega$  in a signal line, and apply current qualification. Please confirm an internal pull down resistor in the block diagram and electrical property of P.5.

#### ●How to select the number of LED lines of the current driver

When the number of LED lines of the current driver is reduced, the un-select can be set the matter that the unnecessary LED1 to 6 terminal is connected to GND. When it uses with 4 lines and so on, it can correspond to it by connecting 2 unnecessary lines to GND.

RSTB is used as a power supply of this decision circuit. The select of the terminal is judged, It has no relation to the logic of PWMPOW and PWMDRV and it isn't judged an unnecessary LED line even if it is connected to GND when it is judged a necessary terminal once. This information can be reset by setting RSTB at 0V.

## Start control and select LED current driver

BD6583MUV-A can control the IC system by RSTB, and IC can power off compulsory by setting 0.2V or below. Also, It powers on PWMPOW is at more than 1.4V and RSTB is at more than 2.25V.

When RSTB=PWMPOW=H, ISETH current is selected at PWMDRV=H and ISETL current is selected at PWMDRV=L.

The starting current in PWMDRV=L sets OFF second time rise of PWMDRV and it becomes 0mA setting after that.

After RSTB sets L once, the starting current can be flowed again by changing it to H.

RSTB	PWMPOW	PWMDRV	IC	LED current
Н	L	L	Off	OFF
Н	Н	L	On	Starting current decided with ISETL
Н	L	Н	Off	OFF
Н	Н	Н	On	Current decided with ISETH
L	L. H	L. H	Off	OFF

#### ● Attendance point of the restriction resistance input to RSTB

When the restriction resistance is input to RSTB, it is necessary to consider the input current of RSTB.

The input current of RSTB changes that depending on the power-supply voltage and the temperature reference to Figure 35.

Because the temperature characteristic of the input current is shown in Figure 35, please choose resistance for which the voltage of the terminal can be guaranteed to 2.1V or more.

And, it has the margin in the decision of resistance, and please confirm and make sure it is no problem in a real application.

The decision example of restriction resistance

- 1.When use the current driver of 6 parallel
  - 2.9V(to RSTB power-supply) restriction resistance value  $\times$  124 $\mu$ A(100 °C input current) > 2.1V restriction resistance value < (2.9-2.1)/124 $\mu$ A=6.45k $\Omega$
- 2. When use the current driver of 3 parallel
  - 2.9V(to RSTB power-supply) restriction resistance value  $\times$  430 $\mu$ A(100 °C input current) > 2.1V restriction resistance value < (2.9-2.1)/430 $\mu$ A=1.86k $\Omega$

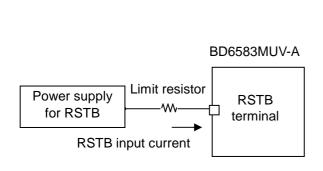


Figure 35. RSTB input current

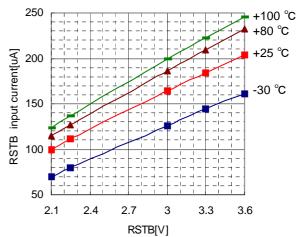


Figure 36. RSTB terminal voltage-RSTB input current (At the time of the current driver 6 lines use)

In addition, the selection number of parallel number of the current driver is changed, the power-supply current of RSTB will be increased. Because the maximum value of the consumption current at the RSTB=2.1V is indicated in the following Table 1, be careful enough when you calculate the restriction resistance.

Table 1. The use	parallel number of current driver at RS	TB=2.1V . 100°C	vs. RSTB input current

Parallel numbers used for current driver	RSTB input current
6	0.12mA
5	0.23mA
4	0.33mA
3	0.43mA
2	0.53mA
1	0.63mA
0	0.74mA

#### ●Start to use PWMPOW terminal for the PWM control, PWM operating

After RSTB and PWMDRV is changing L → H, input PWM to PWMPOW terminal.

There is no constraint in turn of RSTB and PWMDRV.

And, because it corresponds to PWM drive of shorter ON time than soft start time (1ms), when PWMPOW is input H more than three times, the soft start is invalidated and it enable to correspond the high-speed drive. Until RSTB is set L, invalidation of the soft start isn't canceled.

In case of lighting  $\rightarrow$  light off  $\rightarrow$  lighting, when it turns off the lights with PWM=L and It starts without soft start when it sets PWM modulated light again.

But the peak current of the coil changes owing to discharge of output capacitor, It may flow to the over current limit value, as follows Figure 37. Because soft start can be used when it turns off the lights with RSTB=L, The peak current of the coil can be suppressed, as follows Figure 38 and this process of light off is recommended.

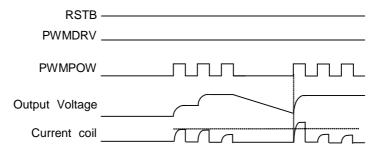


Figure 37. Light off control of PWMPOW pin at PWM control on PWM=L

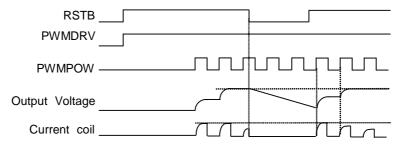


Figure 38. Light off control of PWMPOW pin at PWM control on RSTB=L

#### ● Start to use PWMDRV terminal for the PWM control, PWM operating

After RSTB and PWMPOW is changing L → H, input PWM to PWMDRV terminal.

There is no constraint in turn of RSTB and PWMPOW.

When resistance is set as ISET, after RSTB and PWMPOW is changing  $L \rightarrow H$  as follows Figure 39, when it is not input PWM to PWMDRV pin but input L, boost of DC/DC is unstable state because current driver doesn't pass current.

The starting current is pulled from each LED terminal and pressure up operating is stabilized to escape from this state.

Also, the starting current can be set up by the resistance value connected to the ISETL terminal.

After starting, as the starting current in PWM brightness control become useless, the starting current is set up 0mA at the second rise time of PWMDRV automatically as follows Figure 39.

In case of lighting → light off → lighting, when it turns off the lights with PWM=L and It starts without soft start because of soft

start period was end when it sets PWM modulated light again.

But the peak current of the coil changes owing to discharge of output capacitor, It may flow to the over current limit value, as follows Figure 40. Because soft start can be used when it turns off the lights with RSTB=L, The peak current of the coil can be suppressed, as follows Figure 41 and this process of light off is recommended.

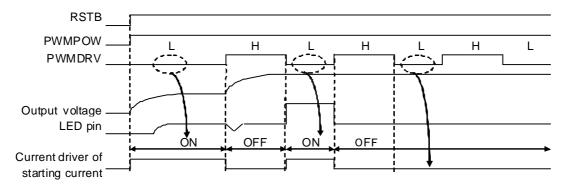
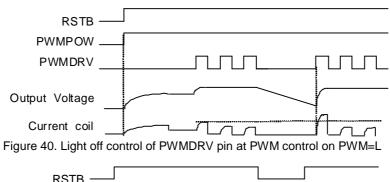


Figure 39. Off timing of starting current at PWMDRV=L



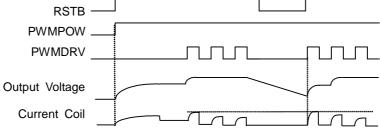


Figure 41. Light off control of PWMDRV pin at PWM control on RSTB=L

#### Brightness control

There are two dimming method is available, first method is analog dimming that apply analog voltage to ISET terminal, and second method is PWM control via digital dimming of PWMPOW or PWMDRV. Because each method has the different merit, please choose a suitable method for the application of use.

Two techniques can be used as digital dimming by the PWM control One is PWM control of current driver, the other is PWM control of power control.

As these two characteristics are shown in the below, selects to PWM control process comply with application.

- •Efficiency emphasis in the low brightness which has an influence with the battery life control
- → 2) Power control PWM

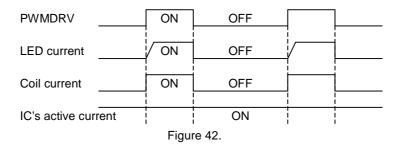
•LED current dispersion emphasis in the PWM brightness control control

→ 1) Current driver PWM

(Reference)

PWM regula	ation process	Efficiency of LED current 0.5mA (PWM Duty=2.5%)	PWM frequency 200Hz Limit dispersion capability of low duty
Currer	nt driver	70%	0.2%
Power	control	93%	0.5%

1) Current driver PWM control is controlled by providing PWM signal to PWMDRV, as it is shown Figure 42. The current set up with ISETH is chosen as the H section of PWMDRV and the current is off as the L section. Therefore, the average LED current is increasing in proportion to duty cycle of PWMDRV signal. This method that it lets internal circuit and DC/DC to work, because it becomes to switch the driver, the current tolerance is a few when the PWM brightness is adjusted, it makes it possible to brightness control until 20µs (MIN0.4% at 200Hz). And, don't use for the brightness control, because effect of ON/OFF changeover is big under 20µs ON time and under 20µs OFF time. There is no effect of ON/OFF changeover at 0% and 100%, so there is no problem on use. Typical PWM frequency is 100Hz to 10kHz. When resistance is set as ISET, RSTB sets H → L, so the starting current may be effective, after RSTB sets L → H, it becomes PWM of the starting current and PWM of ISETH setting current to PWM two times.



2) Power control PWM control is controlled by providing PWM signal to PWMPOW, as it is shown Figure 43. The current setting set up with PWMDRV logic is chosen as the H section and the current is off as the L section. Therefore, the average LED current is increasing in proportion to duty cycle of PWMPOW signal. This method is, because IC can be power-off at off-time, the consumption current can be suppress, and the high efficiency can be available, so it makes it possible to brightness control until 50µs (MIN1% at 200Hz). And, don't use for the brightness control, because effect of power ON/OFF time changeover is big under 50µs ON time and under 50µs OFF time. There is no effect of ON/OFF changeover at 0% and 100%, so there is no problem on use.

Typical PWM frequency is 100Hz to 1kHz. Also, PWM can't control RSTB and PWMPOW at the same time. After RSTB sets H, control PWM only PWMPOW.

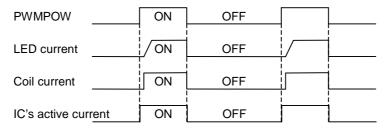


Figure 43.

#### **OLED** current setting range

LED current can set up Normal and Starting setting current.

LED current can set up Normal current by resistance value (RISETH) connecting to ISETH voltage and LED current can set Starting current by resistance value (RISETL) connecting to ISETL voltage.

Setting of each LED current is given as shown below.

Normal current = 20mA ( $24k\Omega/RISETH$ )

Starting constant current = 0.6/RISET L

Also, Normal current setting range is 10mA to 25mA, Starting current setting range is OFF setting or 1μA to 100μA.

LED current can set OFF setting by open setting ISETL pin.

LED current becomes a leak current MAX 1µA at OFF setting.

ISETH Normal current setting example

RISETH	LED current
24kΩ (E24)	20mA
25.5 kΩ (E96)	18.8mA
27 kΩ (E12)	17.8mA
28kΩ (E96)	17.1mA
30kΩ (E24)	16.0mA
33kΩ (E6)	14.5mA

ISETL Starting current s	setting example			
RISETL	LED current			
6.2kΩ (E24)	97µA			
10kΩ (E6)	60µA			
47kΩ (E6)	13µA			
100 kΩ (E6)	6µA			
560 kΩ (E12)	1.1µA			
Connect to VPEC nin	OmΔ			

#### The separations of the IC Power supply and coil Power supply

This IC can work in separating the power source in both IC power supply and coil power supply. With this application, it can obtain that decrease of IC power consumption, and the applied voltage exceeds IC rating 22V.

That application is shown in below Fig 44. The higher voltage source is applied to the power source of coil that is connected from an adapter etc. Next, the IC power supply is connected with a different coil power supply. Under the conditions for inputting from 2.7V to 5.5V into IC VBAT, please follow the recommend design in Fig 40. It connects VBAT terminal and VREG terminal together at IC outside.

When the coil power supply is applied, it is no any problem even though IC power supply is the state of 0V. Although IC power supply is set to 0V, pull-down resistance is arranged for the power off which cuts off the leak route from coil power supply in IC inside, the leak route is cut off. And, there is no power on-off sequence of coil power supply and IC power supply.

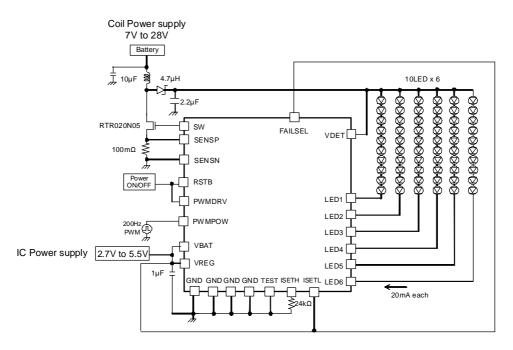


Figure 44. Application at the time of power supply isolation

#### ●The coil selection

The DC/DC is designed by more than 4.7µH. When L value sets to a lower value, it is possibility that the specific sub-harmonic oscillation of current mode DC / DC will be happened.

Please do not let L value to 3.3µH or below.

And, L value increases, the phase margin of DC / DC becomes to zero. Please enlarge the output capacitor value when you increase L value.

Example)

 $4.7\mu H$  = output capacitor  $2.2\mu F/50V$  1pcs  $6.8\mu H$  = output capacitor  $2.2\mu F/50V$  2pcs  $10\mu H$  = output capacitor  $2.2\mu F/50V$  3pcs

This value is just examples, please made sure the final judgment is under an enough evaluation.

#### Layout

In order to make the most of the performance of this IC, its layout pattern is very important. Characteristics such as efficiency and ripple and the likes change greatly with layout patterns, which please note carefully.

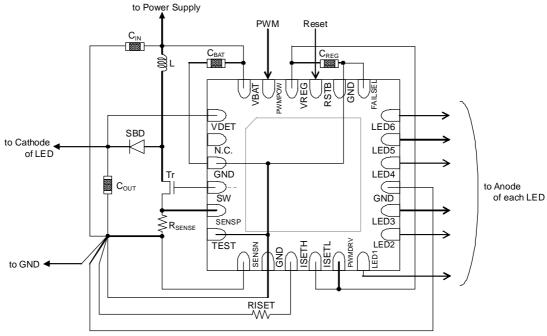


Figure 45. Layout

Connect the input bypath capacitor  $CIN(10\mu F)$  nearest to coil L, as shown in the upper diagram.

Wire the power supply line by the low resistance from CIN to VBAT pin. Thereby, the input voltage ripple of the IC can be reduced. Connect smoothing capacitor CREG of the regulator nearest to between VREG and GND pin, as shown in the upper diagram. Connect schottky barrier diode SBD of the regulator nearest to between coil L and switching transistor Tr.

And connect output capacitor COUT nearest to between CIN and GND pin. Thereby, the output voltage ripple of the IC can be reduced.

Connect switching transistor Tr nearest to SW pin. Wire coil L and switching transistor Tr, current sensing resistor  $R_{\text{SENSE}}$  by the low resistance. Wiring to the SENSP pin isn't Tr side, but connect it from  $R_{\text{SENSE}}$  side. Over current value may become low when wiring from Tr side. Connect  $R_{\text{SENSE}}$  of GND side isolated to SENS pin. Don't wire between  $R_{\text{SENSE}}$  and SNESN pin wiring from  $R_{\text{SENSE}}$  pin to GND pin. And  $R_{\text{SENSE}}$  GND line must be wired directly to GND pin of output capacitor. It has the possibility that restricts the current drive performance by the influence of the noise when other GND is connected to this GND. Connect LED current setting resistor RISET nearest to ISETH pin. There is possibility to oscillate when capacity is added to ISETH terminal, so pay attention that capacity isn't added. And, RISET of GND side must be wired directly to GND pin.

When those pins are not connected directly near the chip, influence is given to the performance of BD6583MUV-A, and may limit the current drive performance. As for the wire to the inductor, make its resistance component small so as to reduce electric power consumption and increase the entire efficiency.

The layout pattern in consideration of these is shown in next page.

## Recommended layout pattern

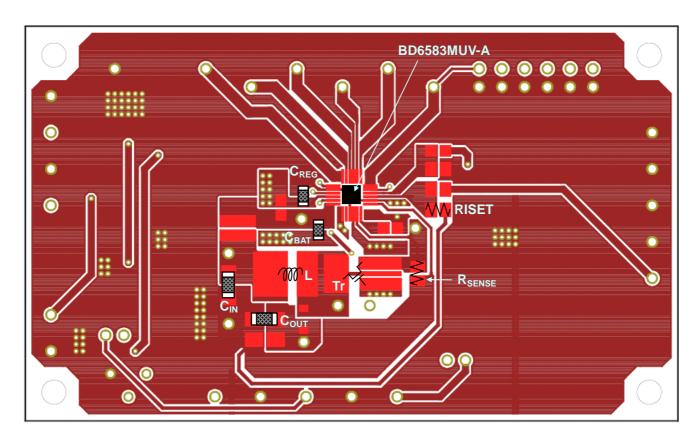


Figure 46. Frontal surface <Top view>

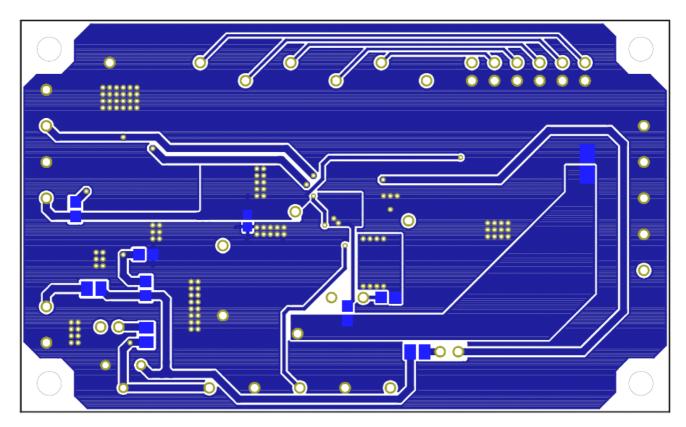


Figure 47. Rear surface <Top view>

#### Selection of external parts

Recommended external parts are as shown below.

When to use other parts than these, select the following equivalent parts.

Coil

) (alua Manufacturar		Due do et accesh ea		Size	DC current	DCR	
Value	Manufacturer	Product number	Vertical	Vertical Horizontal I		(mA)	(Ω)
4.7µH	TOKO	A915AY-4R7M	5.2	5.2	3.0	1870	0.045
4.7µH	TOKO	B1015AS-4R7M	8.4	8.3	4.0	3300	0.038
4.7µH	TOKO	A1101AS-4R7M	4.1	4.1	1.2	1400	0.115
4.7µH	TDK	LTF5022T-4R7N2R0	5.0	5.2	2.2	2000	0.073
4.7µH	TDK	VLP6810T-4R7M1R6	6.3	6.8	1.0	1600	0.167
10µH	TDK	VLP6810T-100M1R1	6.3	6.8	1.0	1100	0.350

Capacitor

-Сарасноі								
Value	Pressure	Manufacturer	Product number	Size			TC	Cap
				Vertical	Horizontal	Height	10	Tolerance
[ Supply vo	oltage capac	itor ]						
10µF	25V	MURATA	GRM31CB31E106K	3.2	1.6	1.6±0.2	В	+/-10%
10µF	10V	MURATA	GRM219R61A106K	2.0	1.25	0.85±0.15	X5R	+/-10%
4.7µF	25V	MURATA	GRM319R61E475K	3.2	1.6	0.85±0.1	X5R	+/-10%
4.7µF	25V	MURATA	GRM21BR61E475K	2.0	1.25	1.25±0.1	X5R	+/-10%
[ Smoothin	g capacitor t	for built-in regula	ator ]					
1µF	10V	MURATA	GRM188B10J105K	1.6	0.8	0.8±0.1	В	+/-10%
[ Output capacitor ]								
1µF	50V	MURATA	GRM31MB31H105K	3.2	1.6	1.15±0.1	В	+/-10%
1µF	50V	MURATA	GRM21BB31H105K	2.0	1.25	1.25±0.1	В	+/-10%
2.2µF	50V	MURATA	GRM31CB31H225K	3.2	1.6	1.6±0.2	В	+/-10%
0.33µF	50V	MURATA	GRM219B31H334K	2.0	1.25	0.85±0.1	В	+/-10%

#### Resistor

1.00.010							
Value	Tolerance	Manufacturer	Product number	Size			
value Tolerand		Manuacturei	Froduct number	Vertical	Horizontal	Height	
[ Resistor for LED current decision <iseth pin="">]</iseth>							
30kΩ	±0.5%	ROHM	MCR006YZPD3002	0.6	0.3	0.23	
[ Resistor for over current decision <sensp pin="">]</sensp>							
100mΩ	±1%	ROHM	MCR10EZHFLR100	2.0	1.25	0.55	

## •SBD

<del></del>						
Pressure	Manufacturer	Product number	Size			
Flessule	Maridiacturei	Product number	Vertical	Horizontal	Height	
60V	ROHM	RB160M-60	3.5	1.6	8.0	

#### •MOS FET Nch

Drocouro	Manufacturer	Product number	Size			Current	Driving
Pressure	Manufacturer		Vertical	Horizontal	Height	ability	voltage
45V	ROHM	RTR020N05	2.8	2.9	1.0	2A	2.5V
60V	ROHM	RSH065N06	6.0	5.0	1.75	6.5A	4.0V

The coil is the part that is most influential to efficiency. Select the coil whose direct current resistor (DCR) and current inductance characteristic is excellent. BD6583MUV-A is designed for the inductance value of  $4.7\mu$ H. Don't uses the inductance value less than  $2.2\mu$ H. Select a capacitor of ceramic type with excellent frequency and temperature characteristics. Further, select Capacitor to be used with small direct current resistance, and pay sufficient attention to the layout pattern shown in Page.21.

#### Attention point of board layout

In board pattern design, the wiring of power supply line should be low Impedance, and put the bypass capacitor if necessary. Especially the wiring impedance must be lower around the DC/DC converter.

#### About heat loss

In heat design, operate the DC/DC converter in the following condition.

(The following temperature is a guarantee temperature, so consider the margin.)

- 1. Periphery temperature Ta must be less than 85 °C.
- 2. The loss of IC must be less than dissipation Pd.

#### Application example

LED current setting controlled ISETH resistor.

19.6kΩ: 24.5mA 24kΩ: 20mA 30kΩ: 16mA 33kΩ: 14.5mA

#### Brightness control

Please input PWM pulse from PWMPOW or PWMDRV terminal. Please refer electrical characteristic p.3 and function (p.12).

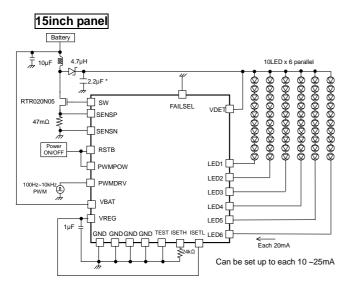


Figure 48. 10 seriesx6 parallel, LED current 20mA setting Current driver PWM application

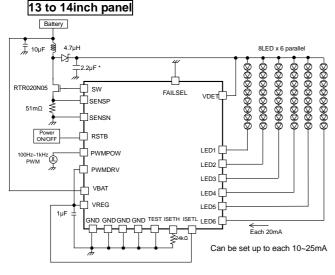


Figure 49. 8 series× parallel, LED current 20mA setting Power control PWM application;:n

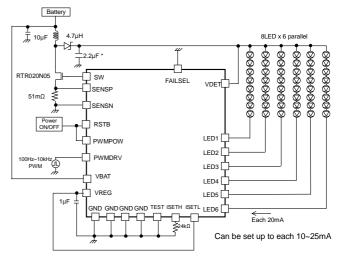


Figure 50. 8 series×6 parallel, LED current 20mA setting Current driver PWM application

· LED current setting controlled ISETH resistor.

19.6kΩ: 24.5mA 24kΩ: 20mA 30kΩ: 16mA 33kΩ: 14.5mA

#### · Brightness control

Please input PWM pulse from PWMPOW or PWMDRV terminal. Please refer electrical characteristic page.3 and function (page.12).

#### 10 to 12inch panel Battery 4.7uF 7LED x 6 paralle 000000000 0000000 00000000 SW FAILSEL VDET LED. LED2 100Hz~10kHz PWM LED3 LED4 LED5 GND GNDGND GND TEST ISETH ISETL LEDG Fach 16mA Can be set up to each 10~25mA

Figure 51. 7 series×6 parallel, LED current 16mA setting Current driver PWM application

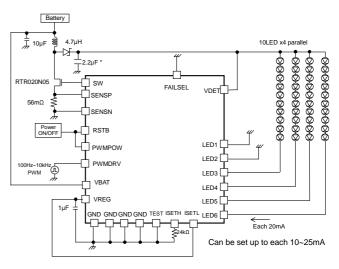


Figure 52. 10 series×4 parallel, LED current 20mA setting Current driver PWM application

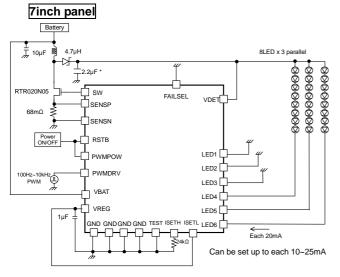


Figure 53. 8 series×3 parallel, LED current 20mA setting Current driver PWM application

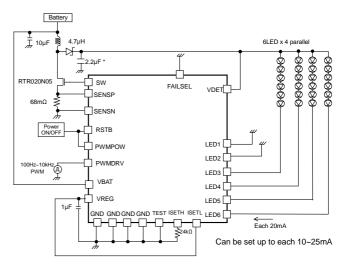


Figure 54. 6 series×4 parallel, LED current 20mA setting Current driver PWM application

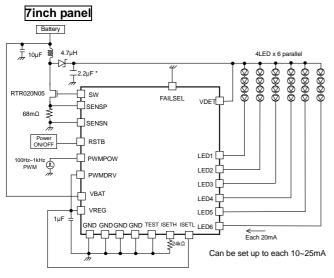
\* Please select the capacitor which the little bias fluctuation.

· LED current setting controlled ISETH resistor.

19.6kΩ: 24.5mA 24kΩ: 20mA 30kΩ: 16mA 33kΩ: 14.5mA

#### · Brightness control

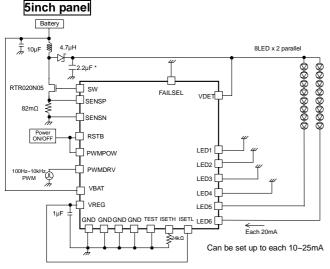
Please input PWM pulse from PWMPOW or PWMDRV terminal. Please refer electrical characteristic page.3 and function (page.12).

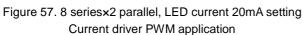


8LED x 3 parallel 000000000 2.2µF ' 00000000 SW FAILSEL SENSE RSTR ON/OFF LED1 φ LED2 LED3 VRAT LED4 LED5 LED6 Can be set up to each 20~50mA

Figure 55. 4 seriesx6 parallel, LED current 20mA setting Power control PWM application

Figure 56. 8 series×3 parallel, LED current 40mA setting Power control PWM application





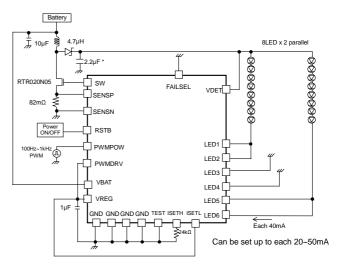


Figure 58. 8 series×2 parallel, LED current 40mA setting Power control PWM application

\* Please select the capacitor which the little bias fluctuation.

LED current setting controlled ISETH resistor.

19.6kΩ: 24.5mA 24kΩ: 20mA 30kΩ: 16mA 33kΩ: 14.5mA

#### · Brightness control

Please input PWM pulse from PWMPOW or PWMDRV terminal. Please refer electrical characteristic page.3 and function (page.12).

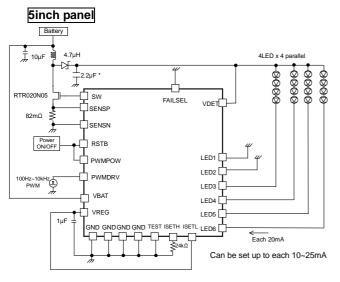


Figure 59. 4 series×4 parallel, LED current 20mA setting Current driver PWM application

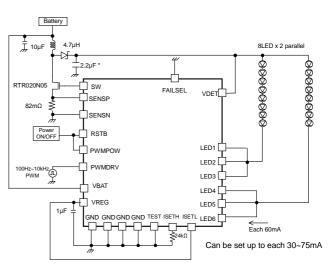


Figure 60. 8 series×2 parallel, LED current 60mA setting Current driver PWM application

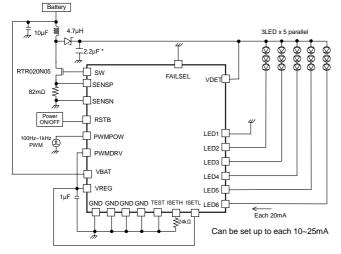


Figure 61. 3 series×5 parallel, LED current 20mA setting Power control PWM application

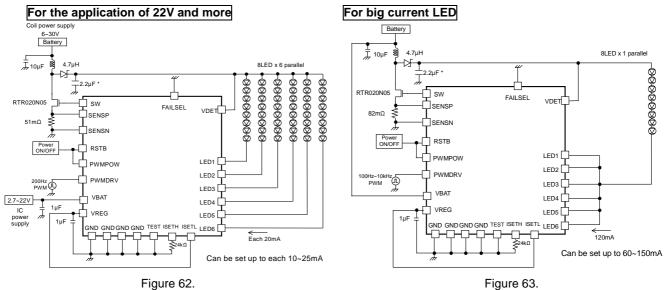
\* Please select the capacitor which the little bias fluctuation.

· LED current setting controlled ISETH resistor.

19.6kΩ: 24.5mA 24kΩ: 20mA 30kΩ: 16mA 33kΩ: 14.5mA

#### · Brightness control

Please input PWM pulse from PWMPOW or PWMDRV terminal. Please refer electrical characteristic page.3 and function (page.12).



guie 62.

## The separation of less than an IC power supply 5V and the coil power supply

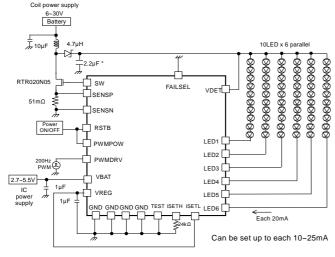


Figure 64.

<sup>\*</sup> Please select the capacitor which the little bias fluctuation.

## Application example of Analog dimming

Control LED current to charged D/A voltage.

Show application example and typ control.

Please decide final value after you evaluated application, characteristic.

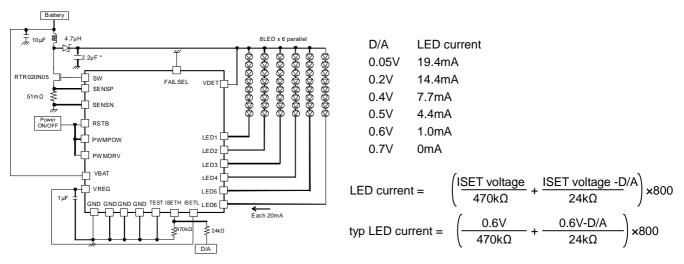


Figure 65. Analog style optical application

<sup>\*</sup> Please select the capacitor which the little bias fluctuation.

#### Operational Notes

#### (1) Absolute Maximum Ratings

An excess in the absolute maximum ratings, such as supply voltage, temperature range of operating conditions, etc., can break down devices, thus making impossible to identify breaking mode such as a short circuit or an open circuit. If any special mode exceeding the absolute maximum ratings is assumed, consideration should be given to take physical safety measures including the use of fuses, etc.

#### (2) Operating conditions

These conditions represent a range within which characteristics can be provided approximately as expected. The electrical characteristics are quaranteed under the conditions of each parameter.

(3) Reverse connection of power supply connector

The reverse connection of power supply connector can break down ICs. Take protective measures against the breakdown due to the reverse connection, such as mounting an external diode between the power supply and the IC's power supply terminal.

#### (4) Power supply line

Design PCB pattern to provide low impedance for the wiring between the power supply and the GND lines. In this regard, for the digital block power supply and the analog block power supply, even though these power supplies has the same level of potential, separate the power supply pattern for the digital block from that for the analog block, thus suppressing the diffraction of digital noises to the analog block power supply resulting from impedance common to the wiring patterns. For the GND line, give consideration to design the patterns in a similar manner.

Furthermore, for all power supply terminals to ICs, mount a capacitor between the power supply and the GND terminal. At the same time, in order to use an electrolytic capacitor, thoroughly check to be sure the characteristics of the capacitor to be used present no problem including the occurrence of capacity dropout at a low temperature, thus determining the constant.

(5) GND voltage

Make setting of the potential of the GND terminal so that it will be maintained at the minimum in any operating state. Furthermore, check to be sure no terminals are at a potential lower than the GND voltage including an actual electric transient.

(6) Short circuit between terminals and erroneous mounting

In order to mount ICs on a set PCB, pay thorough attention to the direction and offset of the ICs. Erroneous mounting can break down the ICs. Furthermore, if a short circuit occurs due to foreign matters entering between terminals or between the terminal and the power supply or the GND terminal, the ICs can break down.

(7) Operation in strong electromagnetic field

Be noted that using ICs in the strong electromagnetic field can malfunction them.

(8) Inspection with set PCB

On the inspection with the set PCB, if a capacitor is connected to a low-impedance IC terminal, the IC can suffer stress. Therefore, be sure to discharge from the set PCB by each process. Furthermore, in order to mount or dismount the set PCB to/from the jig for the inspection process, be sure to turn OFF the power supply and then mount the set PCB to the jig. After the completion of the inspection, be sure to turn OFF the power supply and then dismount it from the jig. In addition, for protection against static electricity, establish a ground for the assembly process and pay thorough attention to the transportation and the storage of the set PCB.

#### (9) Input terminals

In terms of the construction of IC, parasitic elements are inevitably formed in relation to potential. The operation of the parasitic element can cause interference with circuit operation, thus resulting in a malfunction and then breakdown of the input terminal. Therefore, pay thorough attention not to handle the input terminals, such as to apply to the input terminals a voltage lower than the GND respectively, so that any parasitic element will operate. Furthermore, do not apply a voltage to the input terminals when no power supply voltage is applied to the IC. In addition, even if the power supply voltage is applied, apply to the input terminals a voltage lower than the power supply voltage or within the guaranteed value of electrical characteristics.

#### (10) Ground wiring pattern

If small-signal GND and large-current GND are provided, It will be recommended to separate the large-current GND pattern from the small-signal GND pattern and establish a single ground at the reference point of the set PCB so that resistance to the wiring pattern and voltage fluctuations due to a large current will cause no fluctuations in voltages of the small-signal GND. Pay attention not to cause fluctuations in the GND wiring pattern of external parts as well.

#### (11) External capacitor

In order to use a ceramic capacitor as the external capacitor, determine the constant with consideration given to a degradation in the nominal capacitance due to DC bias and changes in the capacitance due to temperature, etc.

(12) Thermal shutdown circuit (TSD)

When junction temperatures become 175℃ (typ) or hi gher, the thermal shutdown circuit operates and turns a switch OFF. The thermal shutdown circuit, which is aimed at isolating the LSI from thermal runaway as much as possible, is not aimed at the protection or guarantee of the LSI. Therefore, do not continuously use the LSI with this circuit operating or use the LSI assuming its operation.

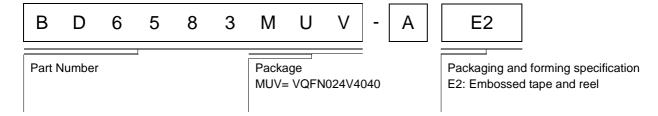
(13) Thermal design

Perform thermal design in which there are adequate margins by taking into account the permissible dissipation (Pd) in actual states of use.

(14) Selection of coil

Select the low DCR inductors to decrease power loss for DC/DC converter.

## Ordering Information



#### Marking Diagram

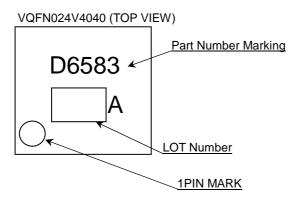
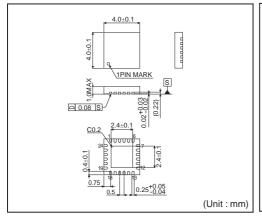


Figure 66. Marking Diagram

#### Physical Dimension Tape and Reel Information

#### VQFN024V4040



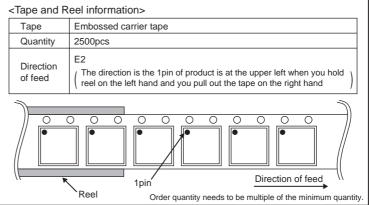


Figure 67. VQFN024V4040

#### Status of this document

The Japanese version of this document is formal specification. A customer may use this translation version only for a reference to help reading the formal version.

If there are any differences in translation version of this document formal version takes priority.

## Revision History

Date	Revision	Changes	
03.Dec.2012	001	New Release	
07.Nov.2016	002	P.4 Pin ESD Type P.13 Figure. 31 Modification P.18 Figure. 41 Modification P. 31 Figure. 66 Modification	

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  - [h] Use of the Products in places subject to dew condensation
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- 7. De-rate Power Dissipation depending on ambient temperature. When used in sealed area, confirm that it is the use in the range that does not exceed the maximum junction temperature.
- 8. Confirm that operation temperature is within the specified range described in the product specification.
- 9. ROHM shall not be in any way responsible or liable for failure induced under deviant condition from what is defined in this document.

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- 2. In principle, the reflow soldering method must be used on a surface-mount products, the flow soldering method must be used on a through hole mount products. If the flow soldering method is preferred on a surface-mount products, please consult with the ROHM representative in advance.

For details, please refer to ROHM Mounting specification

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This Product is electrostatic sensitive product, which may be damaged due to electrostatic discharge. Please take proper caution in your manufacturing process and storage so that voltage exceeding the Products maximum rating will not be applied to Products. Please take special care under dry condition (e.g. Grounding of human body / equipment / solder iron, isolation from charged objects, setting of lonizer, friction prevention and temperature / humidity control).

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  - [b] the temperature or humidity exceeds those recommended by ROHM
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